

P-Channel Enhancement Mode Power MOSFET **MX3415L****DESCRIPTION**

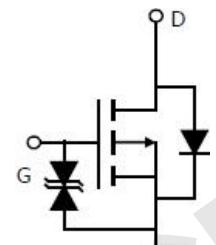
The MX3415L uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as -2.5V. This device is suitable for use as a load switch applications.

**GENERAL FEATURES**

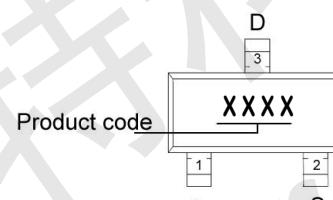
- $V_{DS} = -20V$ ,  $I_D = -4A$
- $R_{DS(ON)}(\text{Typ.}) = 42m\Omega$  @  $V_{GS} = -2.5V$
- $R_{DS(ON)}(\text{Typ.}) = 32m\Omega$  @  $V_{GS} = -4.5V$
- High Power and current handing capability
- Lead free product is acquired
- ESD Rating 4000V HBM

**APPLICATION**

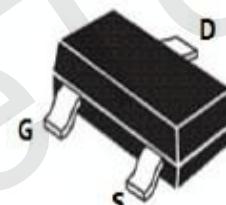
- PWM applications
- Load switch
- Power management

**PINOUT**

Schematic diagram



Marking and pin Assignment



SOT-23 top view

**ORDERING INFORMATION**

Part Number	Storage Temperature	Package	Devices Per Reel
MX3415L	-55°C to 150°C	SOT-23	3000

**ABSOLUTE MAXIMUM RATINGS**( $T_A = 25^\circ C$  unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 10$	V
Drain Current-Continuous( $T_C = 25^\circ C$ )	$I_D$	-4	A
Pulsed Drain Current <sup>(Note1)</sup>	$I_{DM}$	-30	A
Maximum Power Dissipation( $T_C = 25^\circ C$ )	$P_D$	1.4	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

**THERMAL RESISTANCE**

Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	90	°C/W
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Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

P-Channel Enhancement Mode Power MOSFET **MX3415L****ELECTRICAL CHARACTERISTICS** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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**On/Off Characteristics**

Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=-250\mu\text{A}$	-20	-	-	V
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=-20\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	-1	$\mu\text{A}$
Gate-Body Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm 10\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm 10$	$\mu\text{A}$
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=-250\mu\text{A}$	-0.45	-0.65	-1.1	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=-2.5\text{V}, \text{I}_D=-4\text{A}$	-	42	58	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-4.5\text{V}, \text{I}_D=-4\text{A}$	-	32	42	$\text{m}\Omega$

**Dynamic Characteristics**

Forward Transconductance	$\text{g}_{\text{FS}}$	$\text{V}_{\text{DS}}=-5\text{V}, \text{I}_D=-4\text{A}$	-	12	-	S
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=-10\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1.0\text{MHz}$	-	1084	-	pF
Output Capacitance	$\text{C}_{\text{oss}}$		-	140	-	pF
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$		-	111	-	pF
Total Gate Charge	$\text{Q}_{\text{g}}$		-	11	-	nC
Gate-Source Charge	$\text{Q}_{\text{gs}}$	$\text{V}_{\text{DS}}=-10\text{V}, \text{I}_D=-4\text{A}, \text{V}_{\text{GS}}=-4.5\text{V}$	-	1.4	-	nC
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	3.4	-	nC

**Switching Characteristics**<sup>(Note 4)</sup>

Turn-on Delay Time	$\text{t}_{\text{d(on)}}$	$\text{V}_{\text{DS}}=-10\text{V}, \text{V}_{\text{GS}}=-4.5\text{V}, \text{R}_{\text{L}}=2.5\Omega, \text{R}_{\text{G}}=3\Omega$	-	26	-	nS
Turn-on Rise Time	$\text{t}_{\text{r}}$		-	19	-	nS
Turn-Off Delay Time	$\text{t}_{\text{d(off)}}$		-	51	-	nS
Turn-Off Fall Time	$\text{t}_{\text{f}}$		-	62	-	nS

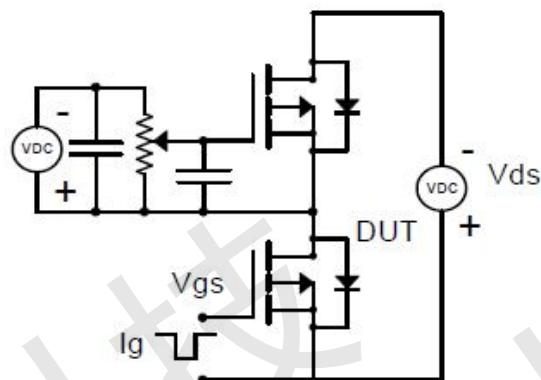
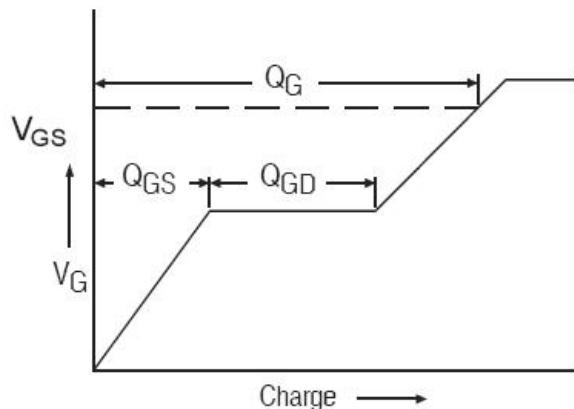
**Drain-Source Diode Characteristics**

Source-Drain Current(Body Diode)	$\text{I}_{\text{SD}}$		-	-	-4	A
Diode Forward Voltage <sup>(Note 3)</sup>	$\text{V}_{\text{SD}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=-4\text{A}$	-	-	-1.2	V

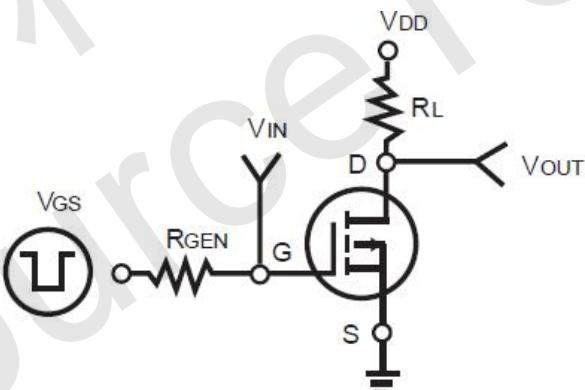
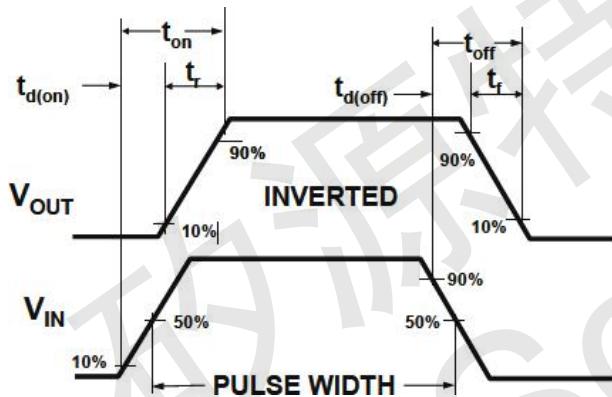


## TEST CIRCUIT

### 1、Gate Charge Test Circuit



### 2、Switch Time Test Circuit and Switching Waveforms



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## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1. Power Dissipation

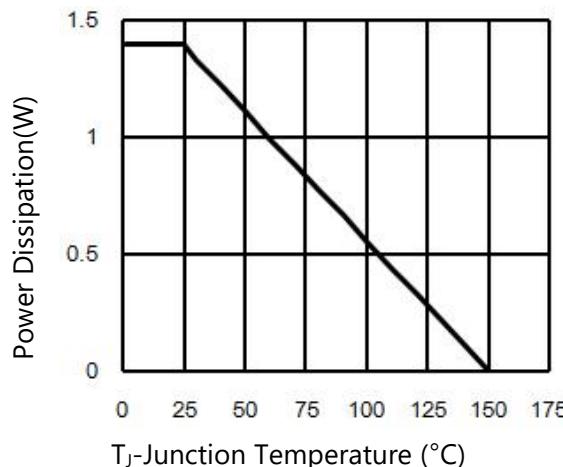


Figure 2. Drain Current

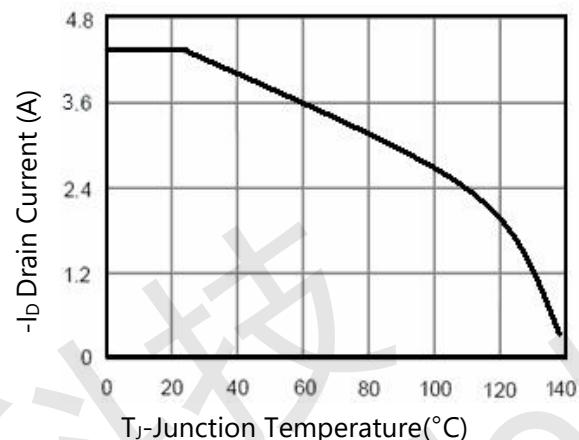


Figure 3. Output Characteristics

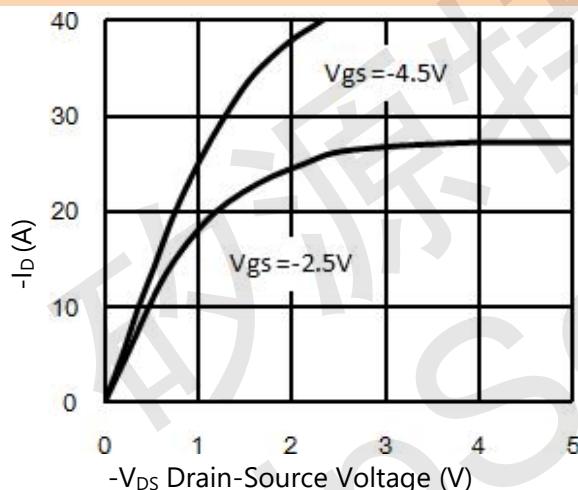
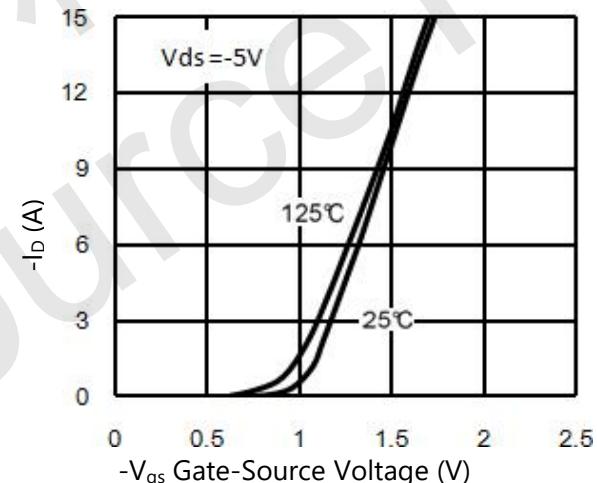
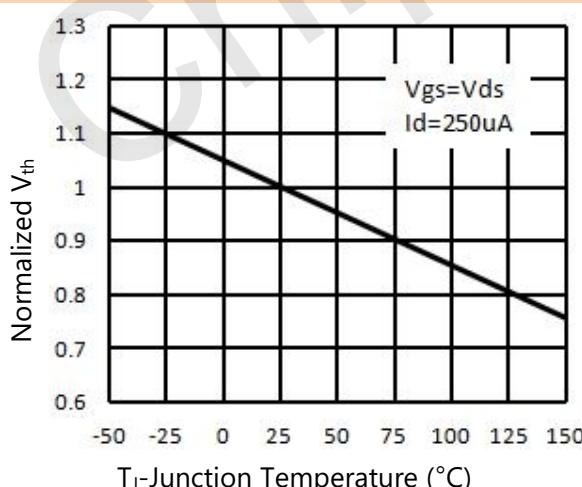
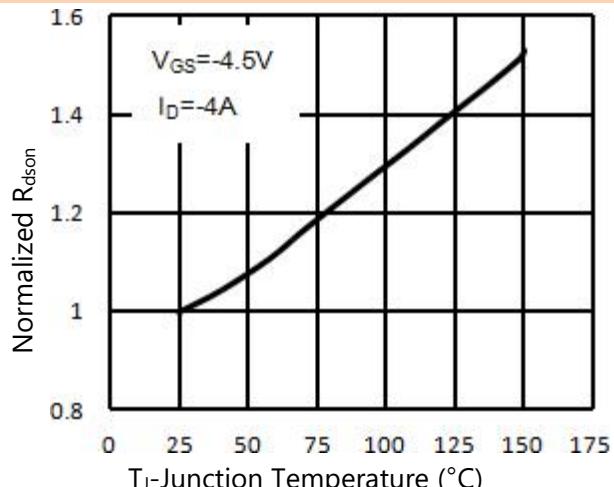


Figure 4. Transfer Characteristics

Figure 5.  $V_{GS(th)}$  vs Junction TemperatureFigure 6.  $R_{DS(on)}$  vs Junction Temperature



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7. Gate Charge Waveforms

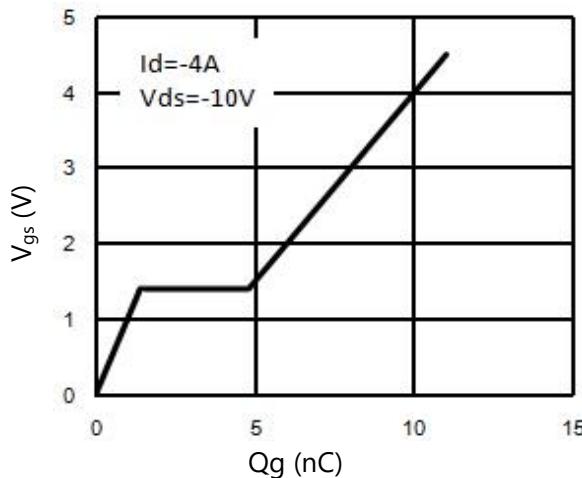


Figure 8. Capacitance

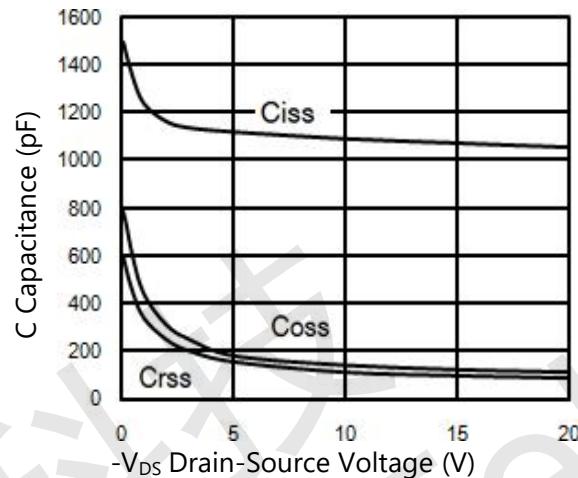


Figure 9. Body-Diode Characteristics

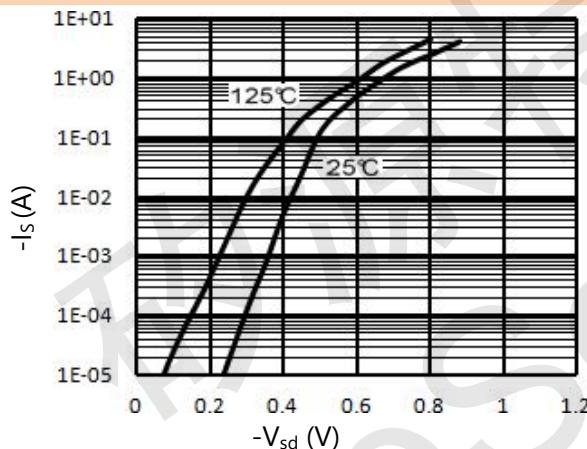
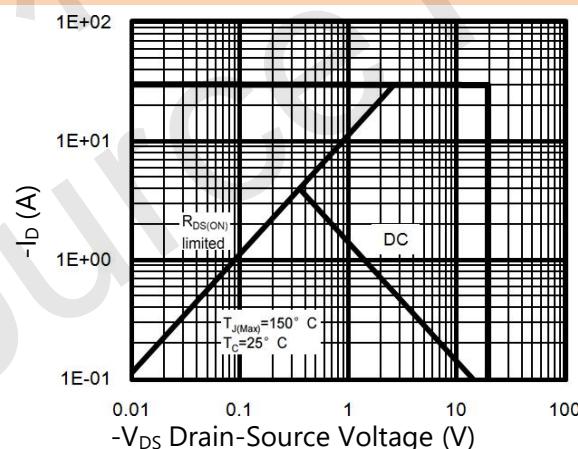


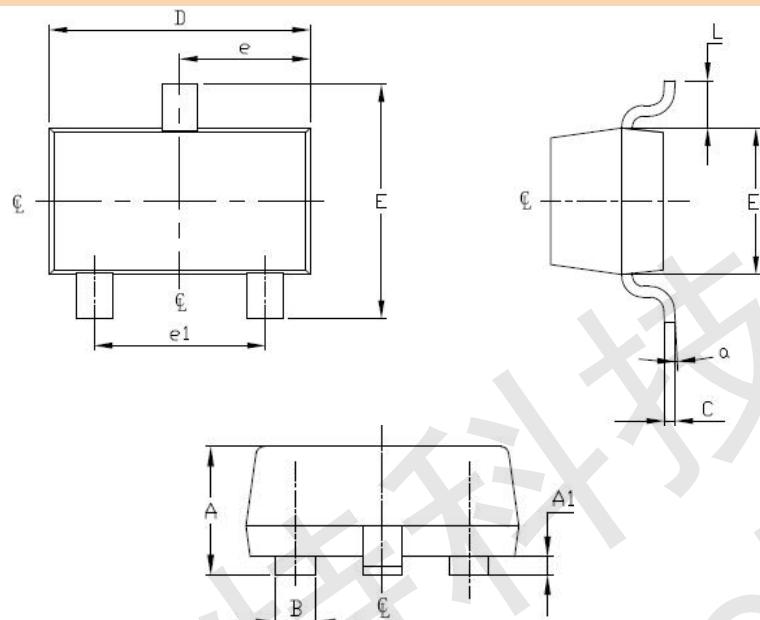
Figure 10. Maximum Safe Operating Area



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## PACKAGE INFORMATION

## SOT-23



Symbol	Dimensions In Millimeters		
	Min.	Typ.	Max.
A	0.9	1.0	1.1
A1	0.00	0.06	0.1
B	0.3	0.4	0.5
C	0.07	0.09	0.18
D	2.8	2.9	3.04
E	2.1	2.33	2.64
E1	1.2	1.3	1.4
e	1.4	1.45	1.5
e1	1.80	1.90	2.00
L	0.45	0.54	0.63
α	0°	2.5°	7°